

Electronic Patent Application Fee Transmittal

Application Number:	10511566								
Filing Date:	13-Apr-2005								
Title of Invention:	Method for forming housings for electronic components and electronic components that are hermetically encapsulated thereby								
First Named Inventor/Applicant Name:	Jurgen Leib								
Filer:	Charles Nicholas Ruggiero/ruth olivo								
Attorney Docket Number:	2133.063USU								
Filed as Large Entity									
U.S. National Stage under 35 USC 371 Filing Fees									
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%; padding: 2px;">Description</th> <th style="width: 15%; padding: 2px;">Fee Code</th> <th style="width: 15%; padding: 2px;">Quantity</th> <th style="width: 15%; padding: 2px;">Amount</th> <th style="width: 25%; padding: 2px;">Sub-Total in USD(\$)</th> </tr> </thead> </table>					Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)					
Basic Filing:									
Pages:									
Claims:									
Independent claims in excess of 3	1614	1	220	220					
Miscellaneous-Filing:									
Petition:									
Patent-Appeals-and-Interference:									
Post-Allowance-and-Post-Issuance:									
Extension-of-Time:									

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				2140